ON Semiconductor

# Product Bulletin

Document # : PB21126X
Issue Date: 27 November 2015

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| **Title of Change:** | Implementation of improved carrier tape for device ESD5004MXTBG (x3DFN 4L) |
| **Effective date:** | 27 November 2015 |
| **Contact information:** | Contact your local ON Semiconductor Sales Office or KaiLoong.Lai@onsemi.com |
| **Type of notification:** | ON Semiconductor will consider this change accepted. |
| **Change category:** | ☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☒ Other Carrier Tape |

**Change Sub-Category(s):**

☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☒ Shipping/Packaging/Marking
☐ Other: _____

**Sites Affected:**

☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ON Seremban, Malaysia ☐ External Foundry/Subcon site(s)

**Description and Purpose:**

This is to announce ON Semiconductor is implementing an improved design carrier tape with raised cross bar between components pockets for its x3DFN 4L packaged devices to prevent unit stick on cover tape issue. No change in quantity per reel and pocket dimensions in this new carrier tape.

**List of affected Standard Parts:**

ESD5004MXTBG